

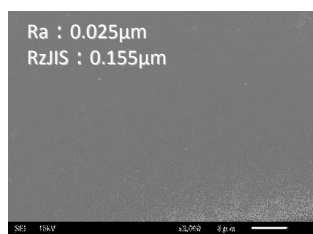
樹脂蝕刻液

Resin Etching Chemical

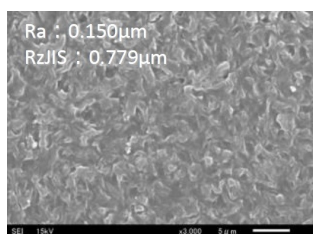
LCP, Polyimide, 可以使用於熱固性樹脂的化學蝕刻

■ LCP (表面粗化及除膠渣)

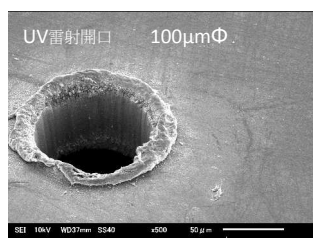
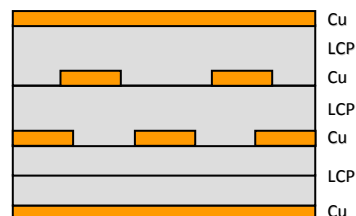
IE-340



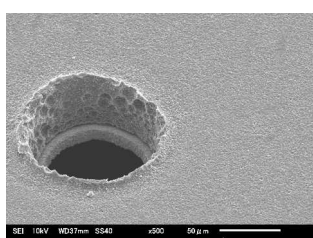
粗化
80°C/3min



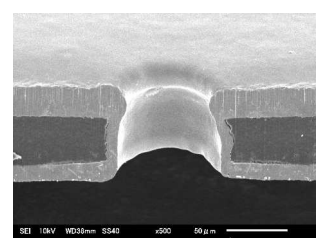
熱壓



除膠渣
80°C/3min



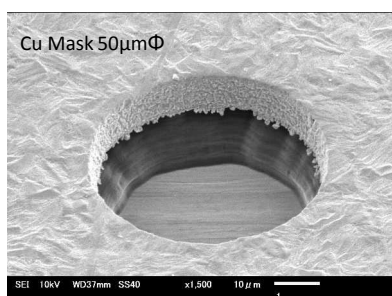
鍍銅



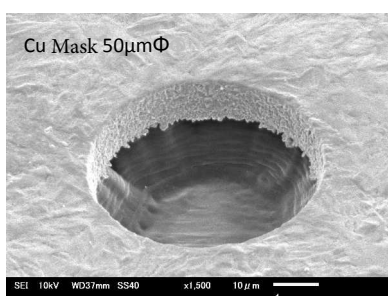
雷射殘渣去除 OK

■ Polyimide (TPI層去除)

IE-303

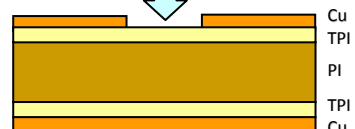


Top/Bottom TPI層去除 OK



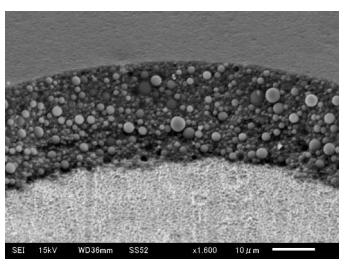
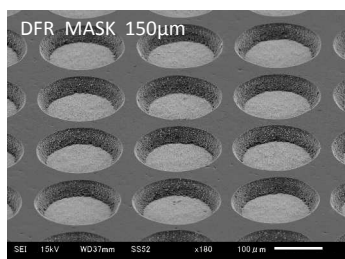
Bottom TPI層殘留 NG

80°C 蝕刻



■ 熱固化性樹脂 IE-330

熱固化性樹脂 (B階段) + 高濃度無機填充物



適用於小直徑開孔與凹洞成形



蝕刻設備